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DATA SHEET

74AVC16835A

18-bit registered driver with Dynamic Controlled Outputs™ (3-State)

Product data
Supersedes data of 2000 Jul 25

2002 Mar 15

Philips
Semiconductors

PHILIPS

18-bit registered driver with Dynamic Controlled Outputs™ (3-State)

74AVC16835A

FEATURES

- Wide supply voltage range of 1.2 V to 3.6 V
- Complies with JEDEC standard no. 8-1A/5/7
- CMOS low power consumption
- Input/output tolerant up to 3.6 V
- DCO (Dynamic Controlled Output) circuit dynamically changes output impedance, resulting in noise reduction without speed degradation
- Low inductance multiple V_{CC} and GND pins for minimum noise and ground bounce
- Power off disables 74AVC16835A outputs, permitting Live Insertion
- Integrated input diodes to minimize input overshoot and undershoot
- Full PC133 solution provided when used with PCK2509S or PCK2510S and CBT16292

DESCRIPTION

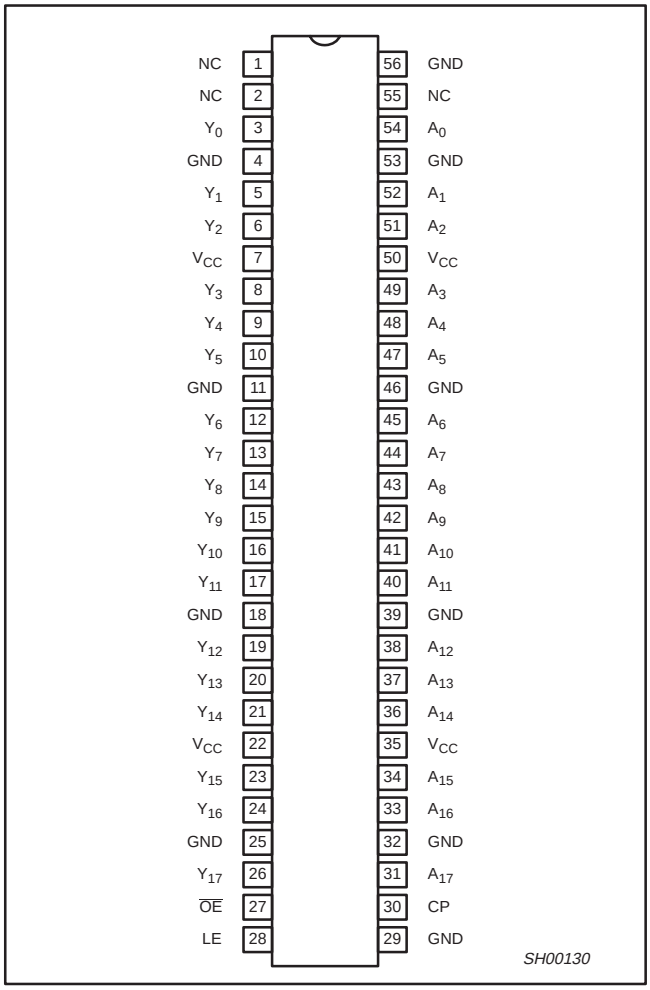
The 74AVC16835A is a 18-bit universal bus driver. Data flow is controlled by output enable ($\overline{OE}$), latch enable (LE) and clock inputs (CP).

This product is designed to have an extremely fast propagation delay and a minimum amount of power consumption.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor (Live Insertion).

A Dynamic Controlled Output (DCO) circuitry is implemented to support termination line drive during transient. See the graphs on page 8 for typical curves.

PIN CONFIGURATION



QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25°C; $t_r = t_f \leq 2.0$ ns; C_L = 30 pF.

SYMBOL	PARAMETER	CONDITIONS		TYPICAL	UNIT
t_{PHL}/t_{PLH}	Propagation delay An to Yn	V_{CC} = 1.8 V V_{CC} = 2.5 V V_{CC} = 3.3 V		2.1 1.7 1.5	ns
t_{PHL}/t_{PLH}	Propagation delay LE to Yn; CP to Yn	V_{CC} = 1.8 V V_{CC} = 2.5 V V_{CC} = 3.3 V		2.2 1.9 1.7	ns
C_I	Input capacitance			3.8	pF
C_{PD}	Power dissipation capacitance per buffer	V_I = GND to V_{CC}[1]	Outputs enabled	25	pF
			Output disabled	6	

NOTE:

1. C_{PD} is used to determine the dynamic power dissipation (P_D in μW):
   $P_D = C_{PD} \times V_{CC}^2 \times f_i + \Sigma (C_L \times V_{CC}^2 \times f_o)$ where: f_i = input frequency in MHz; C_L = output load capacitance in pF; f_o = output frequency in MHz; V_{CC} = supply voltage in V; $\Sigma (C_L \times V_{CC}^2 \times f_o)$ = sum of outputs.

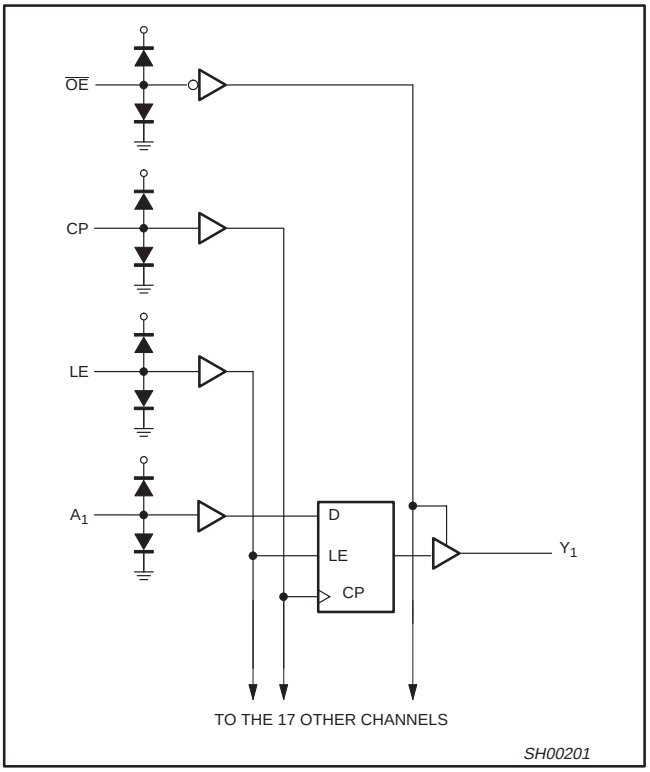
ORDERING INFORMATION

PACKAGES	TEMPERATURE RANGE	ORDER CODE	DRAWING NUMBER
56-Pin Plastic 0.5 mm pitch TSSOP	–40 to +85 °C	74AVC16835ADGG	SOT364-1
56-Pin Plastic 0.4 mm pitch TSSOP (TVSOP)	–40 to +85 °C	74AVC16835ADGV	SOT481-2

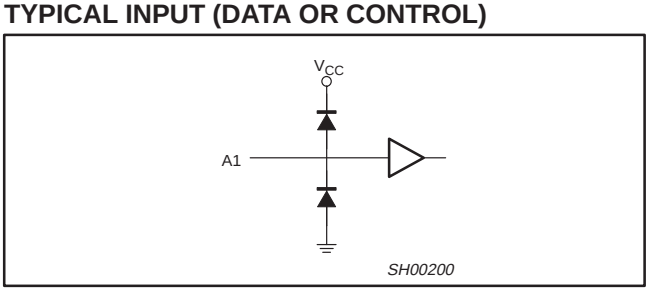
PIN DESCRIPTION

PIN NUMBER	SYMBOL	NAME AND FUNCTION
1, 2, 55	NC	No connection
3, 5, 6, 8, 9, 10, 12, 13, 14, 15, 16, 17, 19, 20, 21, 23, 24, 26	Y_0 to Y_{17}	Data outputs
4, 11, 18, 25, 32, 39, 46, 53, 56	GND	Ground (0V)
7, 22, 35, 50	V_{CC}	Positive supply voltage
27	$\overline{OE}$	Output enable input (active LOW)
28	LE	Latch enable input (active HIGH)
30	CP	Clock input
54, 52, 51, 49, 48, 47, 45, 44, 43, 42, 41, 40, 38, 37, 36, 34, 33, 31	A_0 to A_{17}	Data inputs

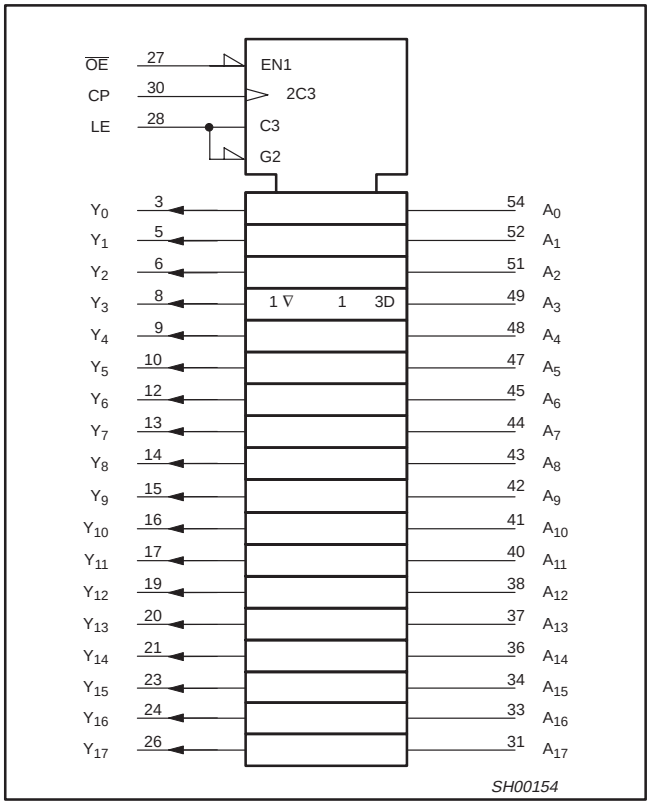
LOGIC SYMBOL



TYPICAL INPUT (DATA OR CONTROL)



LOGIC SYMBOL (IEEE/IEC)

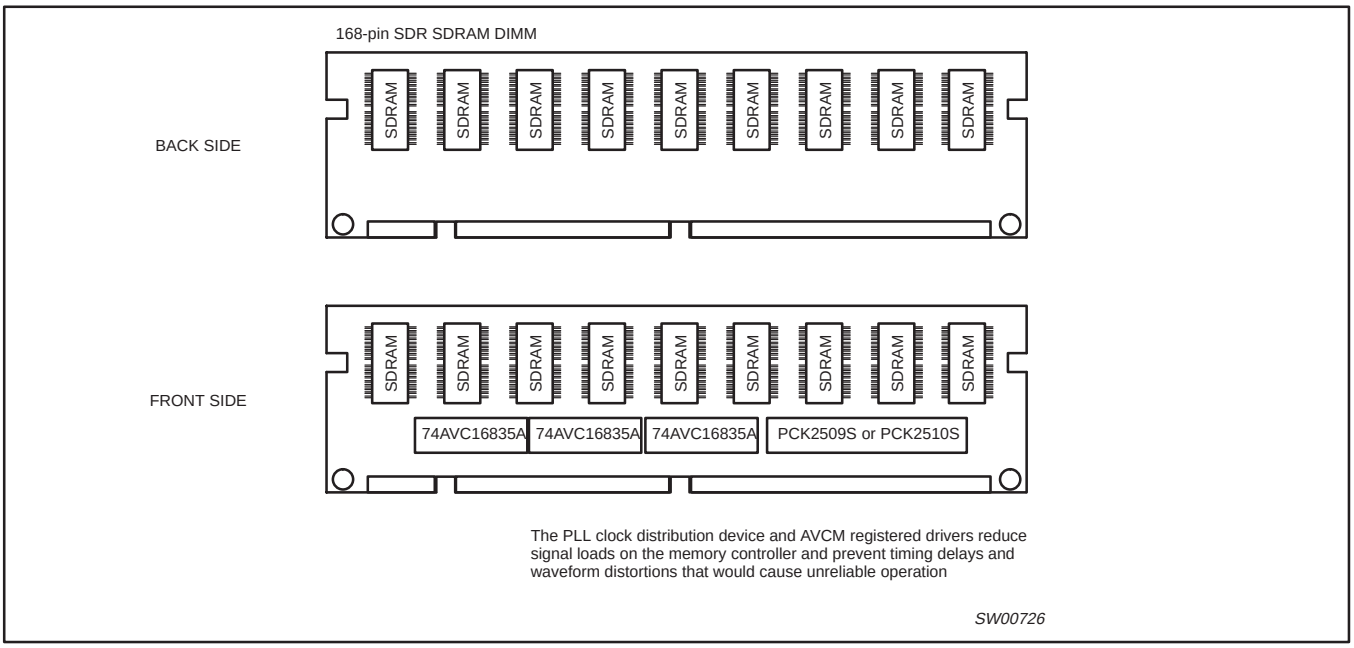


FUNCTION TABLE

INPUTS				OUTPUTS
$\overline{OE}$	LE	CP	A	
H	X	X	X	Z
L	H	X	L	L
L	H	X	H	H
L	L	↑	L	L
L	L	↑	H	H
L	L	H	X	Y_0[1]
L	L	L	X	Y_0[2]

H = HIGH voltage level
L = LOW voltage level
X = Don't care
Z = High impedance "off" state
↑ = LOW-to-HIGH level transition

NOTES:
1. Output level before the indicated steady-state input conditions were established, provided that CP is high before LE goes low.
2. Output level before the indicated steady-state input conditions were established.



RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN	MAX	UNIT
V_{CC}	DC supply voltage (according to JEDEC Low Voltage Standards)		1.65 2.3 3.0	1.95 2.7 3.6	V
	DC supply voltage (for low voltage applications)		1.2	3.6	V
V_I	DC Input voltage range		0	3.6	V
V_O	DC output voltage range; output 3-State		0	3.6	V
	DC output voltage range; output HIGH or LOW state		0	V_{CC}	
T_{amb}	Operating free-air temperature range		–40	+85	°C
t_r, t_f	Input rise and fall times	V_{CC} = 1.65 to 2.3 V V_{CC} = 2.3 to 3.0 V V_{CC} = 3.0 to 3.6 V	0 0 0	30 20 10	ns/V

ABSOLUTE MAXIMUM RATINGS

In accordance with the Absolute Maximum Rating System (IEC 134). Voltages are referenced to GND (ground = 0V).

SYMBOL	PARAMETER	CONDITIONS	RATING	UNIT
V_{CC}	DC supply voltage		–0.5 to +4.6	V
I_{IK}	DC input diode current	$V_I < 0$	–50	mA
V_I	DC input voltage	For all inputs[1]	–0.5 to 4.6	V
I_{OK}	DC output diode current	$V_O > V_{CC}$ or $V_O < 0$	±50	mA
V_O	DC output voltage; output 3-State	Note 1	–0.5 to 4.6	V
V_O	DC output voltage; output HIGH or LOW state	Note 1	–0.5 to V_{CC} +0.5	V
I_O	DC output source or sink current	V_O = 0 to V_{CC}	±50	mA
I_{GND}, I_{CC}	DC V_{CC} or GND current		±100	mA
T_{stg}	Storage temperature range		–65 to +150	°C
P_{TOT}	Power dissipation per package –plastic thin-medium-shrink (TSSOP)	For temperature range: –40 to +125°C above +55°C derate linearly with 8 mW/K	600	mW

NOTE:
1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.

DC ELECTRICAL CHARACTERISTICS

Over recommended operating conditions. Voltage are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS	LIMITS			UNIT
			Temp = –40°C to +85°C			
			MIN	TYP[1]	MAX	
V_{IH}	HIGH level Input voltage	V_{CC} = 1.2 V	V_{CC}	–	–	V
		V_{CC} = 1.65 to 1.95 V	$0.65V_{CC}$	0.9	–	
		V_{CC} = 2.3 to 2.7 V	1.7	1.2	–	
		V_{CC} = 3.0 to 3.6 V	2.0	1.5	–	
V_{IL}	LOW level Input voltage	V_{CC} = 1.2 V	–	–	GND	V
		V_{CC} = 1.65 to 1.95 V	–	0.9	$0.35V_{CC}$	
		V_{CC} = 2.3 to 2.7 V	–	1.2	0.7	
		V_{CC} = 3.0 to 3.6 V	–	1.5	0.8	
V_{OH}	HIGH level output voltage	V_{CC} = 1.65 to 3.6 V; $V_I = V_{IH}$ or V_{IL}; I_O = –100 µA	$V_{CC} - 0.20$	V_{CC}	–	V
		V_{CC} = 1.65 V; $V_I = V_{IH}$ or V_{IL}; I_O = –4 mA	$V_{CC} - 0.45$	$V_{CC} - 0.10$	–	
		V_{CC} = 2.3 V; $V_I = V_{IH}$ or V_{IL}; I_O = –8 mA	$V_{CC} - 0.55$	$V_{CC} - 0.28$	–	
		V_{CC} = 3.0 V; $V_I = V_{IH}$ or V_{IL}; I_O = –12 mA	$V_{CC} - 0.70$	$V_{CC} - 0.32$	–	
V_{OL}	LOW level output voltage	V_{CC} = 1.65 to 3.6 V; $V_I = V_{IH}$ or V_{IL}; I_O = 100 µA	–	GND	0.20	V
		V_{CC} = 1.65 V; $V_I = V_{IH}$ or V_{IL}; I_O = 4 mA	–	0.10	0.45	
		V_{CC} = 2.3 V; $V_I = V_{IH}$ or V_{IL}; I_O = 8 mA	–	0.26	0.55	
		V_{CC} = 3.0 V; $V_I = V_{IH}$ or V_{IL}; I_O = 12 mA	–	0.36	0.70	
I_I	Input leakage current	V_{CC} = 1.65 to 3.6 V; $V_I = V_{CC}$ or GND	–	0.1	2.5	µA
I_{OFF}	3-State output OFF-state current	V_{CC} = 0 V; V_I or V_O = 3.6 V	–	0.1	±10	µA
I_{IHZ}/I_{ILZ}	3-State output OFF-state current	V_{CC} = 1.65 to 3.6 V; $V_I = V_{CC}$ or GND	–	0.1	12.5	µA
I_{OZ}	3-State output OFF-state current	V_{CC} = 1.65 to 2.7 V; $V_I = V_{IH}$ or V_{IL}; $V_O = V_{CC}$ or GND	–	0.1	5	µA
		V_{CC} = 3.0 to 3.6 V; $V_I = V_{IH}$ or V_{IL}; $V_O = V_{CC}$ or GND	–	0.1	10	
I_{CC}	Quiescent supply current	V_{CC} = 1.65 to 2.7 V; $V_I = V_{CC}$ or GND; I_O = 0	–	0.1	20	µA
		V_{CC} = 3.0 to 3.6 V; $V_I = V_{CC}$ or GND; I_O = 0	–	0.2	40	

NOTE:

1. All typical values are at T_{amb} = 25°C.

AC CHARACTERISTICS

GND = 0 V; $t_r = t_f \leq 2.0$ ns; $C_L = 30$ pF

SYMBOL	PARAMETER	WAVEFORM	LIMITS													UNIT
			$V_{CC} = 3.3 \pm 0.3$ V			$V_{CC} = 2.5 \pm 0.2$ V			$V_{CC} = 1.8 \pm 0.15$ V			$V_{CC} = 1.5 \pm 0.1$ V		$V_{CC} = 1.5$ V	$V_{CC} = 1.2$ V	
			MIN	TYP[1]	MAX	MIN	TYP[1]	MAX	MIN	TYP[1]	MAX	MIN	MAX	TYP	TYP	
t_{PHL}/t_{PLH}	Propagation delay An to Yn	1	0.9	1.5	2.5	1.0	1.7	3.0	1.3	2.1	4.2	1.6	5.1	3.6	5.2	ns
	Propagation delay LE to Yn	2	0.9	1.6	2.9	1.1	1.9	3.5	1.3	2.2	4.0	1.6	4.6	2.8	4.2	ns
	Propagation delay CP to Yn	3	0.8	1.7	2.7	1.0	1.8	3.0	1.5	2.2	3.7	1.6	4.6	2.9	4.3	ns
t_{PZH}/t_{PZL}	3-State output enable time $\overline{OE}$ to Yn	6	1.2	2.1	4.0	1.5	2.5	4.5	2.2	3.1	5.8	2.5	7.6	4.4	6.3	ns
t_{PHZ}/t_{PLZ}	3-State output disable time $\overline{OE}$ to Yn	6	1.1	2.6	4.8	1.2	2.2	4.5	2.0	3.1	5.6	2.2	7.6	4.1	5.5	ns
t_W	CP pulse width HIGH or LOW	3	1.0	–	–	1.2	–	–	2.0	–	–	–	–	–	–	ns
	LE pulse width HIGH	2	1.0	–	–	1.2	–	–	2.0	–	–	–	–	–	–	ns
t_{SU}	Set-up time An to CP	5	0	–0.3	–	0	–0.2	–	0	–0.2	–	0.2	–	0	0	ns
	Set-up time An to LE	4	1.0	0.5	–	0.7	0.3	–	1.1	0.6	–	1.6	–	0.9	1.5	ns
t_h	Hold time An to CP	5	1.3	0.6	–	0.7	0.3	–	0.7	0.3	–	0.7	–	0.3	0.1	ns
	Hold time An to LE	4	0.3	0.8	–	0.2	0	–	0.2	–0.2	–	0	–	–0.3	–0.7	ns
f_{max}	Maximum clock pulse frequency	3	500	–	–	400	–	–	250	–	–	–	–	–	–	MHz

NOTE:

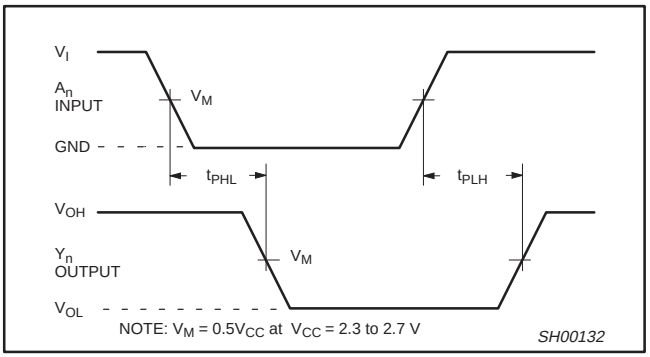
1. All typical values are measured at $T_{amb} = 25°C$ and at $V_{CC} = 1.8$ V, 2.5 V, 3.3 V.

AC WAVEFORMS FOR V_{CC} = 3.0 V TO 3.6 V RANGE

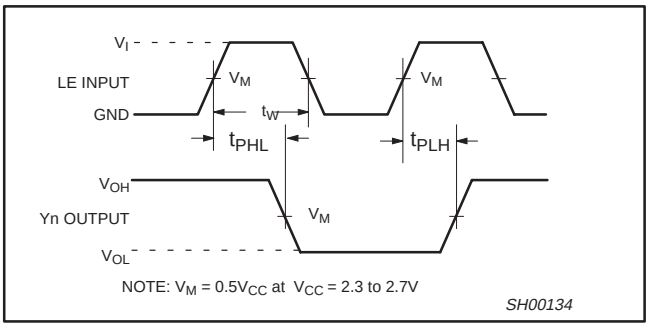
$V_M = 0.5\ V_{CC}$
$V_X = V_{OL} + 0.300\ V$
$V_Y = V_{OH} – 0.300\ V$
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_I = V_{CC}$

AC WAVEFORMS FOR V_{CC} = 2.3 V TO 2.7 V AND V_{CC} < 2.3 V RANGE

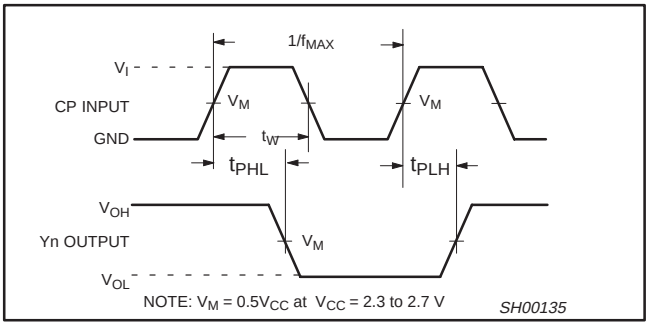
$V_M = 0.5\ V_{CC}$
$V_X = V_{OL} + 0.15\ V$
$V_Y = V_{OH} – 0.15\ V$
V_{OL} and V_{OH} are the typical output voltage drop that occur with the output load.
$V_I = V_{CC}$



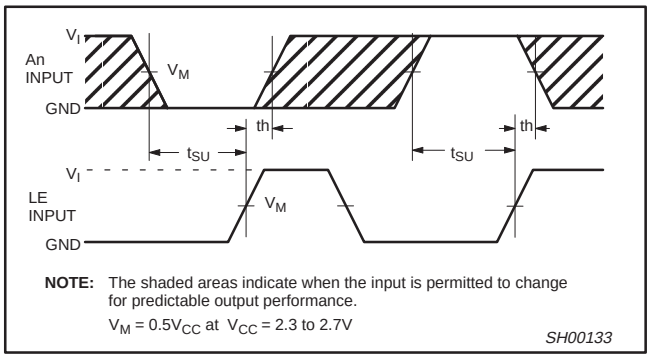
Waveform 1. Input (An) to output (Yn) propagation delay



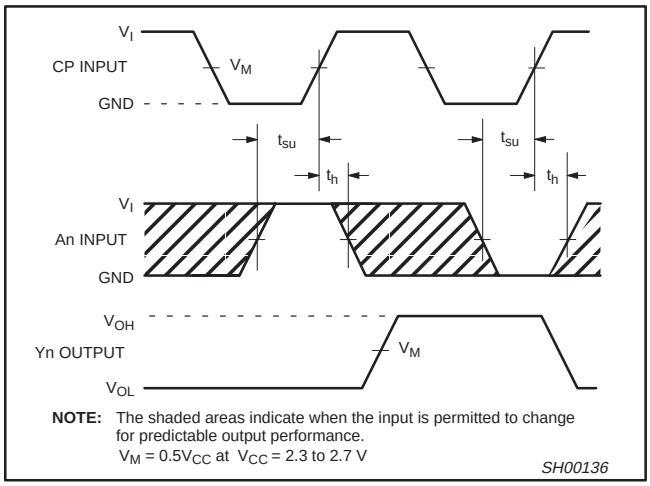
Waveform 2. Latch enable input (LE) pulse width, the latch enable input to output (Yn) propagation delays.



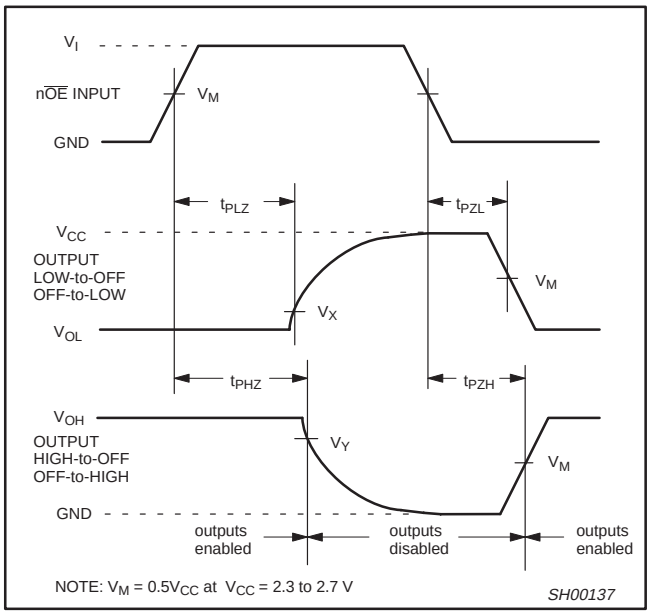
Waveform 3. The clock (CP) to Yn propagation delays, the clock pulse width and the maximum clock frequency.



Waveform 4. Data set-up and hold times for the An input to the LE input

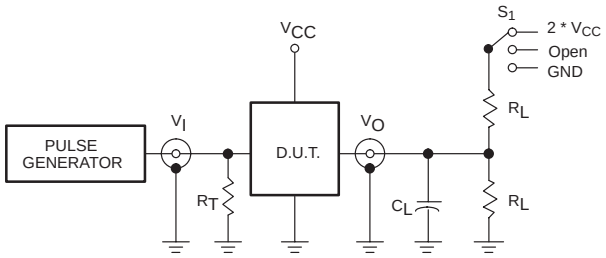


Waveform 5. Data set-up and hold times for the An input to the clock CP input



Waveform 6. 3-State enable and disable times

TEST CIRCUIT



Test Circuit for switching times

DEFINITIONS

R_L = Load resistor

C_L = Load capacitance includes jig and probe capacitance

R_T = Termination resistance should be equal to Z_{OUT} of pulse generators.

SWITCH POSITION

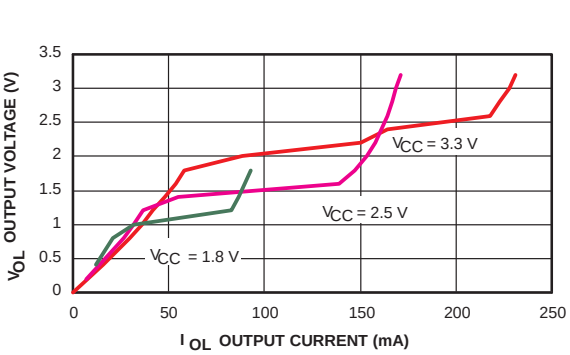
TEST	S_1
t_{PLH}/t_{PHL}	Open
t_{PLZ}/t_{PZL}	2 * V_{CC}
t_{PHZ}/t_{PZH}	GND

V_{CC}	V_I	R_L
< 2.3 V	V_{CC}	1000 Ω
2.3–2.7 V	V_{CC}	500 Ω
3.0 V	V_{CC}	500 Ω

SV01018

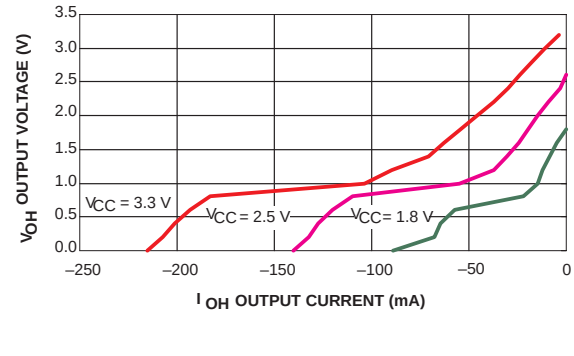
Figure 1. Load circuitry for switching times

GRAPHS



SH00204

Figure 2. Output voltage (V_{OL}) vs. output current (I_{OL})

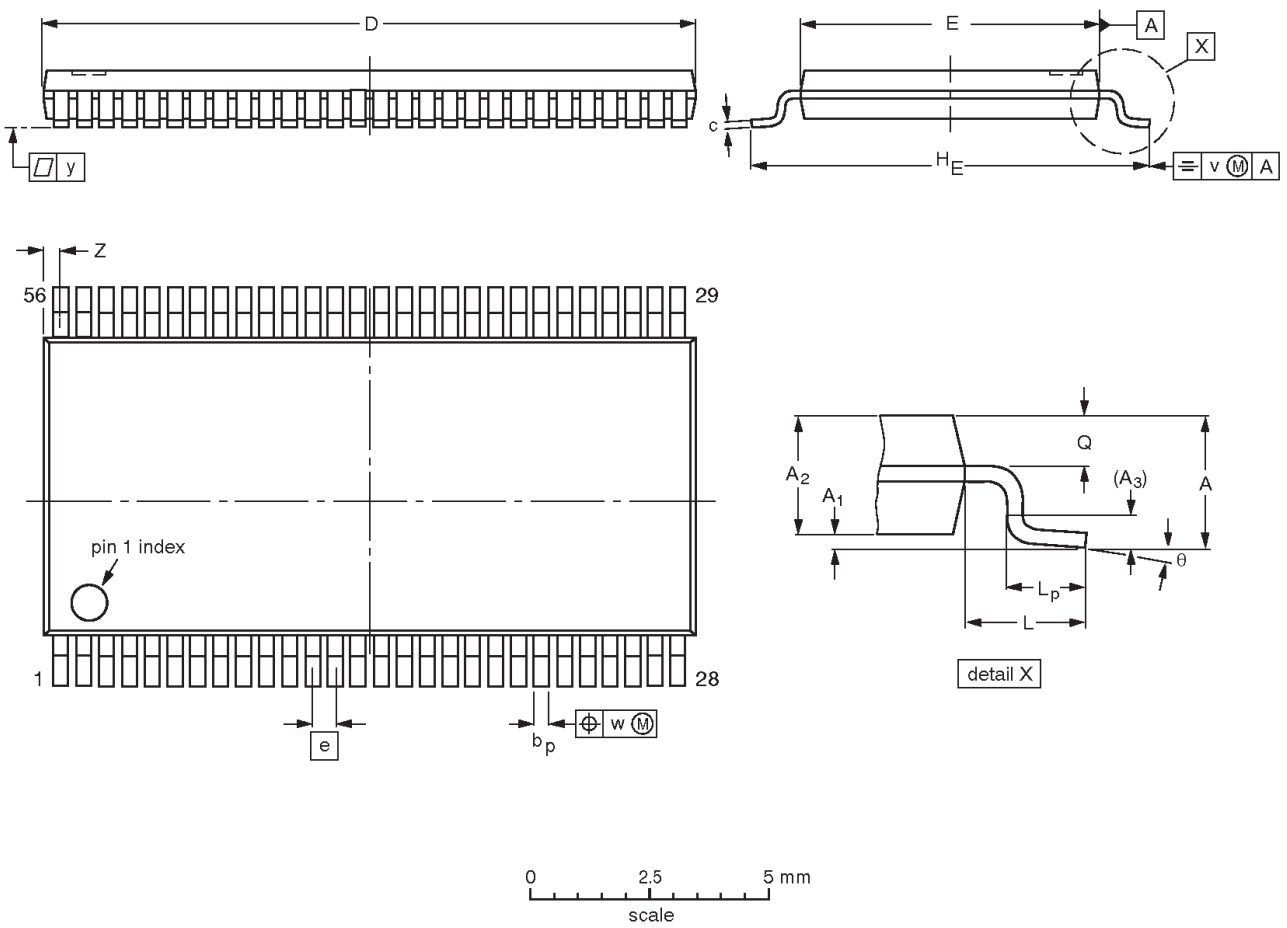


SH00205

Figure 3. Output voltage (V_{OH}) vs. output current (I_{OH})

A Dynamic Controlled Output (DCO) circuit is designed in. During the transition, it initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figures 2 and 3 show V_{OL} vs. I_{OL} and V_{OH} vs. I_{OH} curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DCO circuit provides a maximum dynamic drive that is equivalent to a high drive standard output device.

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 6.1 mm SOT364-1



DIMENSIONS (mm are the original dimensions).

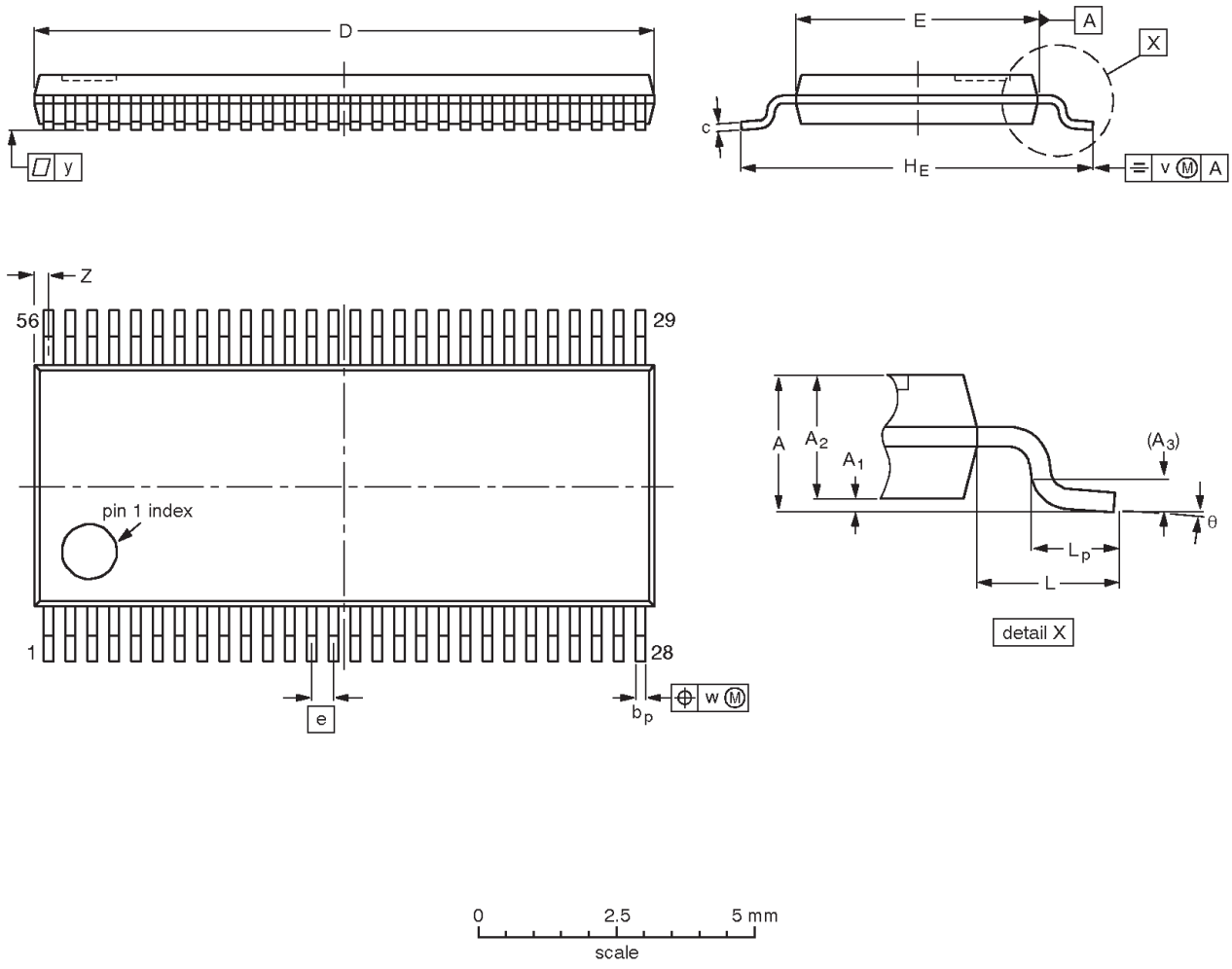
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(2)}$	e	H_E	L	L_p	Q	v	w	y	Z	θ
mm	1.2	0.15 0.05	1.05 0.85	0.25	0.28 0.17	0.2 0.1	14.1 13.9	6.2 6.0	0.5	8.3 7.9	1.0	0.8 0.4	0.50 0.35	0.25	0.08	0.1	0.5 0.1	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES					EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	EIAJ				
SOT364-1		MO-153					~~95-02-10~~ 99-12-27

TSSOP56: plastic thin shrink small outline package; 56 leads; body width 4.4 mm SOT481-2



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	v	w	y	Z (1)	θ
mm	1.2	0.15 0.05	1.05 0.80	0.25	0.23 0.13	0.20 0.09	11.4 11.2	4.5 4.3	0.4	6.6 6.2	1	0.75 0.45	0.2	0.07	0.08	0.4 0.1	8° 0°

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT481-2	- - -	MO-194	- - -			01-11-24

NOTES

18-bit registered driver with Dynamic Controlled Outputs™ (3-State)

74AVC16835A

Data sheet status

Data sheet status [1]	Product status [2]	Definitions
Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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